

A full-day Short Course on Introduction to Advanced Packaging to Monash University Malaysia & Taylor's University Malaysia

27th July 2024



The poster features logos for NXP, IEEE Electronics Packaging Society, Monash University Malaysia, and Taylor's University Malaysia at the top. The main title is 'NXP TRAINING WORKSHOP - INTRODUCTION TO IC PACKAGING -'. Below this, it says 'GET READY FOR EXPLOSIVE GROWTH IN SEMICONDUCTOR INDUSTRY'. The date and time are '27 JULY 2024 (SATURDAY) 9.00 AM - 4.00 PM' with the venue 'VENUE: NXP MALAYSIA SDNBHD'. A circular portrait of Mr. Azham Mohd Sukemi is shown, with his name and title 'OUR HONORABLE SPEAKER MR. AZHAM MOHD SUKEMI TECHNICAL DIRECTOR PACKAGE INNOVATION NXP MALAYSIA SDN. BHD.' listed below. A starburst graphic at the bottom left says '3RD & 4TH YEAR STUDENTS ONLY!'. A small text box at the bottom right states: 'Participants who can commit to the entire duration will receive a certificate from EPS, which holds significant value for securing job in semiconductor industry. EPS will also assist in distributing the certified participants' resumes to the Semiconductors industry for potential job opportunities.'

- NXP Semiconductors and IEEE EPS Malaysia have jointly organized a full-day course on Introduction to Advanced Packaging for engineering students from Monash University Malaysia and Taylor's University Malaysia. The main purpose is to build talent pool to support the growth of Semiconductor industry in Malaysia and all over the world.
- The event took place at the main auditorium of NXP Semiconductors factory in Sungai Way Free Industrial Zone.
- Besides the topic, students were also introduced to working environment in semiconductor packaging such as clean room environment, smock (attire), and roles & responsibility of process engineers. At the end of the course, students were given questions to test their understanding on the topics.
- > 40 students attended the short course, with lunch sponsored by NXP Semiconductors Malaysia.